

ABSTRACT

A bonding pad structure having an electrically conductive capping layer. An electrically conductive first supporting layer is disposed immediately under the electrically conductive capping layer, without any intervening layers between the electrically conductive capping layer and the electrically conductive first supporting layer. The electrically conductive first supporting layer is configured as one of a sheet having no voids and a sheet having slotted voids in a first direction. An electrically conductive second supporting layer is disposed under the electrically conductive first supporting layer. The electrically conductive second supporting layer is configured as one of a sheet having slotted voids in the first direction, a sheet having slotted voids in a second direction, and a sheet having checkerboard voids.

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